EXTEC® CORP.

DIAMOND WAFERING BLADES

EXTEC Diamond Wafering Blades are available in high or low concentration in 3" (76 mm), 4" (102 mm), 5" (127 mm), 6" (152 mm), 7" (178 mm) and 8" (203 mm) diameters. High concentration is designed for routine use with most metals and ceramics. Low concentration is recommended for brittle materials such as ceramics, glass, carbides and other heat resistant materials. EXTEC EP Wafering Blades are specifically manufactured for soft and gummy materials. EXTEC I CBN (Cubic Boron Nitride) Wafering Blades are preferred for Iron and Cobalt Base Alloys, Nickel Base Super Alloys and Lead Base Alloys. DW Diamond Wafering Blades or AC Advanced Ceramic Diamond Wafering Blades come complete with a Dressing Stick. EP Diamond Wafering Blades do not require a Dressing Stick. EXTEC Universal or EXTEC Water Soluble Cutting Fluid is recommended for precision cutting and reduced cutting time.

CATALOG NUMBER	DESCRIPTION	UNIT
12043	EXTEC AC Dressing Stick 1” x 1/2” x 3” (25.4 mm x 12.7 mm x 76 mm)	Each
12045	EXTEC DW Dressing Stick 1” x 1/2” x 3” (25.4 mm x 12.7 mm x 76 mm)	Each
12050	EXTEC Universal Cutting Fluid	qt (0.95 l)
12052	EXTEC Universal Cutting Fluid	gal (3.8 l)
12065	EXTEC Water Soluble Cutting Fluid	qt (0.95 l)
12067	EXTEC Water Soluble Cutting Fluid	gal (3.8 l)
EXTEC Diamond Wafering Blade, High Concentration Recommended for: metal matrix composites, titanium, thermal spray coatings, printed circuit boards, bones		
12200	3" Dia. x 0.006" Thickness x 1/2” Arbor (76 mm x 0.15 mm x 12.7 mm)	Each
12205	4" Dia. x 0.012" Thickness x 1/2” Arbor (102 mm x 0.3 mm x 12.7 mm)	Each
12210	5" Dia. x 0.015" Thickness x 1/2” Arbor (127 mm x 0.4 mm x 12.7 mm)	Each
12215	6" Dia. x 0.020" Thickness x 1/2” Arbor (152 mm x 0.5 mm x 12.7 mm)	Each
12220	7" Dia. x 0.025" Thickness x 1/2” Arbor (178 mm x 0.6 mm x 12.7 mm)	Each
12218	8" Dia. x 0.035" Thickness x 1/2” Arbor (203 mm x 0.9 mm x 12.7 mm)	Each
EXTEC Diamond Wafering Blade, High Concentration Recommended for: aggressive cutting, ferrous and non-ferrous materials		
12252	5" Dia. x 0.020" Thickness x 1/2” Arbor (127 mm x 0.5 mm x 12.7 mm)	Each
12253	7" Dia. x 0.025" Thickness x 1/2” Arbor (178 mm x 0.6 mm x 12.7 mm)	Each
12254	8" Dia. x 0.035" Thickness x 1/2” Arbor (203 mm x 0.9 mm x 12.7 mm)	Each
EXTEC EP Diamond Wafering Blade, High Concentration Recommended for: polymers, rubber, soft gummy materials		
12222	4" Dia. x 0.012" Thickness x 1/2” Arbor (102 mm x 0.3 mm x 12.7 mm)	Each
12224	5" Dia. x 0.015" Thickness x 1/2” Arbor (127 mm x 0.4 mm x 12.7 mm)	Each
12226	7" Dia. x 0.025" Thickness x 1/2” Arbor (178 mm x 0.6 mm x 12.7 mm)	Each
12228	8" Dia. x 0.035" Thickness x 1/2” Arbor (203 mm x 0.9 mm x 12.7 mm)	Each

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EXTEC Diamond Wafering Blade, Low Concentration Recommended for: ceramics, glass, alumina, zirconia, concrete, electronic substrates		
12230	3" Dia. x 0.006" Thickness x 1/2" Arbor (76 mm x 0.15 mm x 12.7 mm)	Each
12235	4" Dia. x 0.012" Thickness x 1/2" Arbor (102 mm x 0.3 mm x 12.7 mm)	Each
12236	4" Dia. x 0.020" Thickness x 1/2" Arbor (102 mm x 0.5 mm x 12.7 mm)	Each
12240	5" Dia. x 0.015" Thickness x 1/2" Arbor (127 mm x 0.4 mm x 12.7 mm)	Each
12245	6" Dia. x 0.020" Thickness x 1/2" Arbor (152 mm x 0.5 mm x 12.7 mm)	Each
12250	7" Dia. x 0.025" Thickness x 1/2" Arbor (178 mm x 0.6 mm x 12.7 mm)	Each
12248	8" Dia. x 0.035" Thickness x 1/2" Arbor (203 mm x 0.9 mm x 12.7 mm)	Each
EXTEC Diamond Wafering Blade, Low Concentration Recommended for: structural ceramics, boron nitride, silicon nitride		
12257	5" Dia. x 0.020" Thickness x 1/2" Arbor (127 mm x 0.5 mm x 12.7 mm)	Each
12258	7" Dia. x 0.025" Thickness x 1/2" Arbor (178 mm x 0.6 mm x 12.7 mm)	Each
12259	8" Dia. x 0.035" Thickness x 1/2" Arbor (203 mm x 0.9 mm x 12.7 mm)	Each
EXTEC AC (Advanced Ceramic) Diamond Wafering Blade, Low Concentration Recommended for: medium ceramics, GaAs, AIN, glass fiber composites, electron packages		
12190	3" Dia. x 0.006" Thickness x 1/2" Arbor (76 mm x 0.15 mm x 12.7 mm)	Each
12192	4" Dia. x 0.012" Thickness x 1/2" Arbor (102 mm x 0.3 mm x 12.7 mm)	Each
12194	5" Dia. x 0.020" Thickness x 1/2" Arbor (127 mm x 0.5 mm x 12.7 mm)	Each
12196	7" Dia. x 0.025" Thickness x 1/2" Arbor (178 mm x 0.6 mm x 12.7 mm)	Each
12198	8" Dia. x 0.025" Thickness x 1/2" Arbor (203 mm x 0.9 mm x 12.7 mm)	Each
EXTEC Diamond Wafering Blade, Low Concentration Recommended for: soft friable ceramics, composites with fine reinforcing media CaF, MgF, carbon composites		
12193	3" Dia. x 0.006" Thickness x 1/2" Arbor (76 mm x 0.15 mm x 12.7 mm)	Each
12195	5" Dia. x 0.015" Thickness x 1/2" Arbor (127 mm x 0.4 mm x 12.7 mm)	Each
EXTEC I CBN (Cubic Boron Nitride) Wafering Blade, Low Concentration Recommended for: iron and cobalt based allows, nickel based super alloys and lead based alloys		
12345	3" Dia. x 0.006" Thickness x 1/2" Arbor (76 mm x 0.15 mm x 12.7 mm)	Each
12350	4" Dia. x 0.012" Thickness x 1/2" Arbor (102 mm x 0.3 mm x 12.7 mm)	Each
12355	5" Dia. x 0.015" Thickness x 1/2" Arbor (127 mm x 0.4 mm x 12.7 mm)	Each
12260	6" Dia. x 0.020" Thickness x 1/2" Arbor (152 mm x 0.5 mm x 12.7 mm)	Each
12265	7" Dia. x 0.025" Thickness x 1/2" Arbor (178 mm x 0.6 mm x 12.7 mm)	Each
12268	8" Dia. x 0.035" Thickness x 1/2" Arbor (203 mm x 0.9 mm x 12.7 mm)	Each